

**IN THE CLAIMS:**

1. A method for making a packaged integrated circuit (IC) comprising:  
forming a heat spreader in a sheet of thermally conductive material;  
attaching an IC die in a die up configuration to the heat spreader at a first location of  
the heat spreader;  
singulating the heat spreader with the attached IC die from a remaining portion of the  
sheet wherein the heat spreader extends to at least a portion of an edge of the  
packaged IC.
2. The method of claim 1 wherein the forming the heat spreader further includes:  
forming a plurality of wire bond windows in the heat spreader located between the  
first location and an outer portion of the heat spreader.
3. The method of claim 2 wherein forming the wire bond windows further includes  
forming at least five thermal connection structures thermally coupling the first portion of the  
heat spreader with the outer portion of the heat spreader, each thermal connection structure  
defining at least a portion of a wire bond window of the plurality of wire bond windows.
4. The method of claim 1 wherein the forming the heat spreader further includes forming  
singulation slots in the sheet around an outer portion of the heat spreader, at least portions of  
the singulation slots being defined by portions of an edge of the outer portion of the heat  
spreader.
5. The method of claim 1 further comprising:  
reducing the thickness of the sheet at a location at an edge of the heat spreader;  
wherein the singulating the heat spreader with the attached IC die from a remaining  
portion of the sheet further includes cutting the sheet at the location at the edge  
of the outer portion.
6. The method of claim 1 further comprising:  
encapsulating the IC die attached to the heat spreader, the encapsulating further  
including placing a mold die against the sheet including against the heat  
spreader at a location near the edge of the heat spreader.

7. A packaged integrated circuit (IC) comprising:  
an IC die;  
a heat spreader, the IC die thermally coupled to the heat spreader at a first location of the heat spreader in a die up configuration, the heat spreader extends to at least a portion of an edge of the packaged IC.
8. The packaged IC of claim 7 wherein the heat spreader defines a wire bond window located between the first location and an outer portion of the heat spreader.
9. The packaged IC of claim 8 further comprising:  
a wire bond extending from a die bond pad on the IC die into the wire bond window to a wire bond finger.
10. - 14. (Canceled)
15. A method for making a packaged integrated circuit (IC) comprising:  
forming a heat spreader in a sheet of thermally conductive material, wherein the forming includes reducing the thickness of the sheet at a location at an edge of the heat spreader;  
attaching an IC die to the heat spreader at a first location of the heat spreader;  
singulating the heat spreader with the attached IC die from a remaining portion of the sheet, wherein the singulating further includes cutting the sheet at the location at the edge of the heat spreader.
16. The method of claim 15 wherein the reducing the thickness of the sheet further includes etching a portion of the sheet at the location at the edge.
17. The method of claim 16 wherein the etching a portion of the sheet further includes etching a first planar side of the sheet at the location and not a second planar side of the sheet at the location, wherein the first planar side is opposite the second planar side.
18. The method of claim 17 wherein the die is attached to the heat spreader at a second planar side of the sheet.

19. The method of claim 15 wherein the reducing the thickness of the sheet further includes coining a portion of the sheet at the location at the edge.
20. The method of claim 15 wherein the forming a heat spreader further includes forming a first singulation slot in the sheet and forming a second singulation slot in the sheet generally orthogonal with respect to the first singulation slot, wherein the location extends from the first singulation slot to the second singulation slot.
21. The method of claim 15 wherein the edge of the heat spreader includes four sides, wherein the location at the edge of the heat spreader is located along at least a majority of a side of the four sides.
22. The method of claim 15 wherein:  
the forming a heat spreader in the sheet further includes forming a plurality of heat spreaders in the sheet;  
wherein the reducing the thickness of the sheet at a location at an edge of the heat spreader further includes reducing the thickness of the sheet at a plurality of locations with each location of the plurality at an edge of two adjacent heat spreaders of the plurality of heat spreaders;  
wherein the attaching an IC die to the heat spreader further includes attaching each of a plurality of IC die to each of the plurality of heat spreaders at a first location of the each of the heat spreader;  
encapsulating at least a portion of a first side of the sheet including encapsulating the plurality of IC dies in an encapsulate;  
wherein the singulating the heat spreader with the attached IC die from a remaining portion of the sheet further includes singulating the plurality of heat spreaders with an attached IC die of the plurality of IC die, wherein the cutting the sheet at the location at the edge of the heat spreader further includes cutting the sheet of at the plurality of locations and cutting the encapsulate at locations above the plurality of locations.
23. The method of claim 15 wherein the location is at a corner of the heat spreader.
24. The method of claim 23 wherein the reducing the thickness of the sheet at the location at the edge of the heat spreader further includes reducing the thickness of the sheet at

a plurality of locations at the edge wherein each location of the plurality is at a corner of the heat spreader.

25. The method of claim 15 wherein:

the sheet has a strip form, the strip form having a length and a width;

the forming a heat spreader in a sheet further includes forming a plurality of heat spreaders in the sheet along the length of the sheet in a one deep configuration along the width.

26. - 39. (Canceled)